

Product / Package Information

Package	LGA (Flipchip)
Body Size (mm)	5 X 5
I/O Count	32
Terminal Finish	NiPdAu
MS Number	MS012824B + MS012362D

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.53E-02	89.40	894000	57.20	571970
Thermosets	Epoxy resin	Proprietary	1.41E-03	5.00	50000	3.20	31989
Thermosets	Phenol Resin	Proprietary	1.27E-03	4.50	45000	2.88	28790
Other inorganic materials	Other	Proprietary	2.83E-04	1.00	10000	0.64	6398
Other inorganic materials	Carbon Black	1333-86-4	2.83E-05	0.10	1000	0.06	640
Subtotal			2.83 E-02	100.00	1000000	63.98	639787

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.41 E-03	55.71	557100	14.50	144968
Thermosets	Proprietary Resin Mixture	Trade secret	2.30 E-03	20.04	200400	5.21	52148
Glass	Glass Fabric	65997-17-3	1.64 E-03	14.23	142300	3.70	37029
Other inorganic materials	Talc containing no asbestiform fibers	14807-96-6	1.38 E-05	0.12	1200	0.03	312
Other inorganic materials	Silica, amorphous	Trade secret	5.06 E-05	0.44	4400	0.11	1145
Other inorganic materials	Barium sulfate	7727-43-7	9.20 E-05	0.8	8000	0.21	2082
Other inorganic materials	Epoxy resin	85954-11-6	2.30 E-05	0.2	2000	0.05	520
Other inorganic materials	Phosphin oxide derivative	Trade secret	1.38 E-05	0.12	1200	0.03	312
Other inorganic materials	Other	Trade secret	7.27 E-04	6.32	63200	1.64	16446
Other organic materials	Gold	7440-57-5	1.61 E-05	0.14	1400	0.04	364
Other organic materials	Palladium	7440-05-3	1.61 E-05	0.14	1400	0.04	364
Other organic materials	Nickel	7440-02-0	2.00 E-04	1.74	17400	0.45	4528
Subtotal			1.15E-02	100.00	1000000	26.02	260220

Wafer Bump

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin and its alloys	Tin	7440-31-5	1.12 E-05	98.2	982000	0.03	253
Tin and its alloys	Silver	7440-22-4	2.05 E-07	1.8	18000	0.00	5
Subtotal			1.14 E-05	100.0	1000000	0.03	258

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.40 E-03	100.0	1000000	9.96	99646

UBM

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.21 E-07	79.87	798700	0.001	5
Other non-ferrous metals and alloys	Titanium	7440-32-6	5.57 E-08	20.13	201300	0.000	1
Subtotal			2.77 E-07	100.0	1000000	0.00	6

Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polyimide 1	70485-58-4	3.67 E-06	100.00	1000000	0.01	83
Subtotal			3.67 E-06	100.0	1000000	0.01	83

Package Totals			Weight (g) 4.42 E-02			Percentage (%) 100.00	PPM 1000000
-----------------------	--	--	--------------------------------	--	--	---------------------------------	-----------------------

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary